

# MECHANICAL CASE OUTLINE

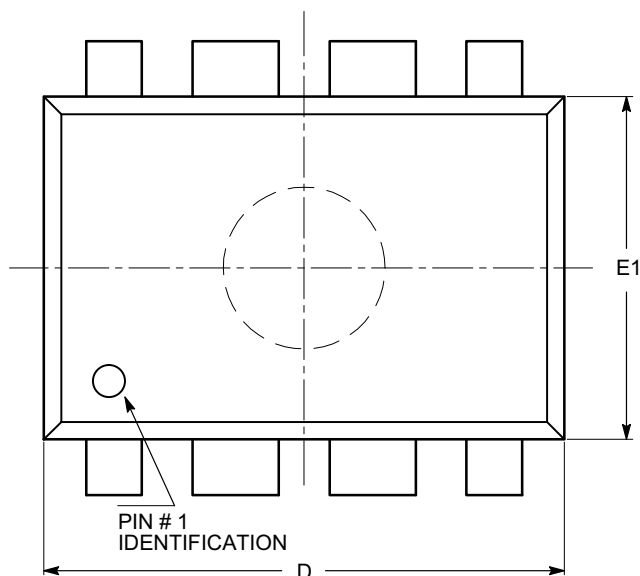
## PACKAGE DIMENSIONS

ON Semiconductor®



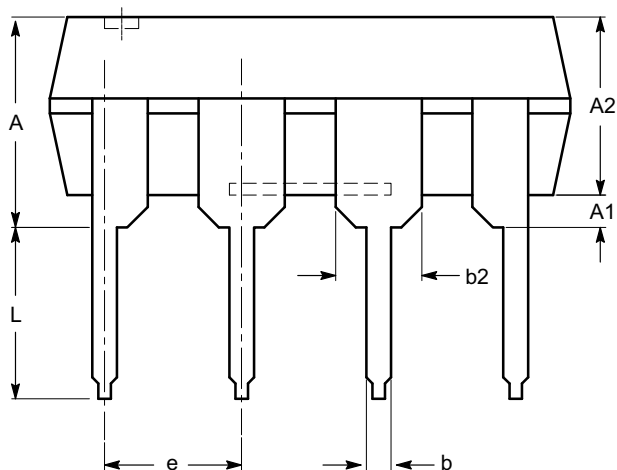
PDIP-8, 300 mils  
CASE 646AA-01  
ISSUE A

DATE 18 MAR 2009

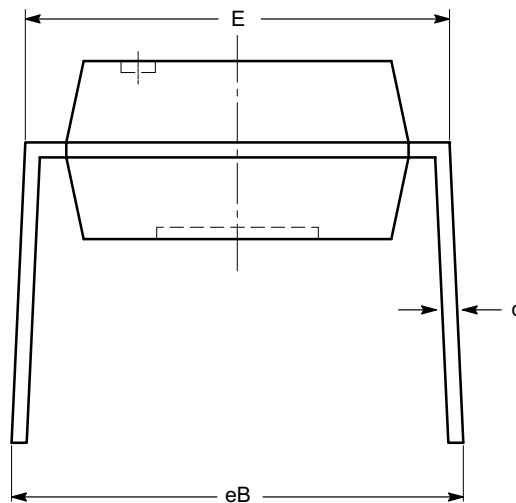


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			5.33
A1	0.38		
A2	2.92	3.30	4.95
b	0.36	0.46	0.56
b2	1.14	1.52	1.78
c	0.20	0.25	0.36
D	9.02	9.27	10.16
E	7.62	7.87	8.25
E1	6.10	6.35	7.11
e	2.54 BSC		
eB	7.87		10.92
L	2.92	3.30	3.80



SIDE VIEW



END VIEW

**Notes:**

- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MS-001.

<b>DOCUMENT NUMBER:</b>	98AON34122E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	PDIP-8, 300 MILS	<b>PAGE 1 OF 2</b>

